



## DCR1150N42

# **Phase Control Thyristor**

DS5967-3 August 2014 (LN31841)

### **FEATURES**

- Double Side Cooling
- High Surge Capability

### **APPLICATIONS**

- Medium Voltage Soft Starts
- High Voltage Power Supplies
- Static Switches

### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages V <sub>DRM</sub> and V <sub>RRM</sub> V	Conditions
DCR1150N42 DCR1150N40	4200 4000	$\begin{split} T_{vj} &= \text{-}40^{\circ}\text{C to 125}^{\circ}\text{C}, \\ I_{DRM} &= I_{RRM} = 100\text{mA}, \\ V_{DRM}, V_{RRM}t_p &= 10\text{ms}, \\ V_{DSM}\&V_{RSM} &= \\ V_{DRM}\&V_{RRM} + 100V \\ respectively \end{split}$

Lower voltage grades available.

### **KEY PARAMETERS**

$V_{DRM}$	4200V
$I_{T(AV)}$	1150A
I <sub>TSM</sub>	16800A
dV/dt*	1500V/μs
dI/dt	1000A/µs

## \* Higher dV/dt selections available

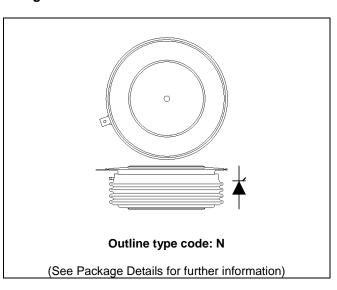


Fig. 1 Package outline

## **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

#### DCR1150N42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.





## **CURRENT RATINGS**

## $T_{case} = 60$ °C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Side Cooled				
I <sub>T(AV)</sub>	Mean on-state current	Half wave resistive load	1150	Α
I <sub>T(RMS)</sub>	RMS value	-	1806	А
I <sub>T</sub>	Continuous (direct) on-state current	-	1665	А

## **SURGE RATINGS**

Symbol Parameter		Test Conditions	Max.	Units
I <sub>TSM</sub>	Surge (non-repetitive) on-state current	10ms half sine, T <sub>case</sub> = 125°C	16.8	kA
I <sup>2</sup> t I <sup>2</sup> t for fusing		$V_R = 0$	1.41	MA <sup>2</sup> s

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Condition	s	Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance – junction to case	Double side cooled	DC	-	0.0221	°C/W
		Single side cooled	Anode DC		0.041	°C/W
			Cathode DC	ı	0.0516	°C/W
R <sub>th(c-h)</sub>	Thermal resistance – case to heatsink	Clamping force 23 kN	Double side		0.004	°C/W
		(with mounting compound)	Single side	ı	0.008	°C/W
$T_{vj}$	Virtual junction temperature	Blocking V <sub>DRM</sub> / <sub>VRRM</sub>			125	°C
T <sub>stg</sub>	Storage temperature range			-55	125	°C
F <sub>m</sub>	Clamping force			20.0	25.0	kN





## **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I <sub>RRM</sub> /I <sub>DRM</sub>	Peak reverse and off-state current	At V <sub>RRM</sub> /V <sub>DRM</sub> , T <sub>case</sub> = 125°C		-	100	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V <sub>DRM</sub> , T <sub>j</sub> = 125°C, ga	ate open	-	1500	V/µs
dl/dt	Rate of rise of on-state current	From 67% V <sub>DRM</sub> to 2x I <sub>T(AV)</sub>	Repetitive 50Hz	-	250	A/µs
		Gate source 30V, 10Ω,	Non-repetitive	-	1000	A/µs
		$t_r < 0.5 \mu s, T_j = 125^{\circ}C$				
V <sub>T(TO)</sub>	Threshold voltage – Low level	300A to 850A at T <sub>case</sub> = 125°	С	-	0.86	V
	Threshold voltage – High level	850A to 4000A at T <sub>case</sub> = 125	850A to 4000A at T <sub>case</sub> = 125°C		1.0	V
r <sub>T</sub>	On-state slope resistance – Low level	300A to 850A at T <sub>case</sub> = 125°C		-	0.611	mΩ
	On-state slope resistance – High level	850A to 4000A at T <sub>case</sub> = 125°C		-	0.444	mΩ
t <sub>gd</sub>	Delay time	$V_D = 67\% V_{DRM}$ , gate source 30V, $10\Omega$		-	3	μs
		$t_r = 0.5 \mu s, T_j = 25^{\circ}C$				
tq	Turn-off time	$T_j$ = 125°C,I <sub>peak</sub> = 1000A, $t_p$ = $V_{RM}$ = 100V, $dI/dt$ = -5A/ $\mu$ s,	= 1000us,		800	μs
		dV <sub>DR</sub> /dt = 20V/μs linear to 25	500V			
I <sub>RR</sub>	Reverse recovery current	$I_T$ = 1000A, $t_p$ = 1000us, $T_j$ = 125°C, dI/dt = - 5A/ $\mu$ s, $V_R$ = 100V		81	121	Α
Qs	Stored charge			2000	3500	μC
IL	Latching current	$T_j = 25$ °C, $V_D = 5V$		-	3	А
lн	Holding current	$T_j = 25^{\circ}C, R_{G-K} = \infty, I_{TM} = 500$	0A, I <sub>T</sub> = 5A	-	300	mA



## **GATE TRIGGER CHARACTERISTICS AND RATINGS**

Symbol	Parameter Test Conditions		Max.	Units
$V_{GT}$	Gate trigger voltage	$V_{DRM} = 5V$ , $T_{case} = 25$ °C	1.5	V
$V_{GD}$	Gate non-trigger voltage	At 50% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	0.4	V
I <sub>GT</sub>	Gate trigger current	$V_{DRM} = 5V$ , $T_{case} = 25$ °C	350	mA
I <sub>GD</sub>	Gate non-trigger current	At 50% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	15	mA

## **CURVES**

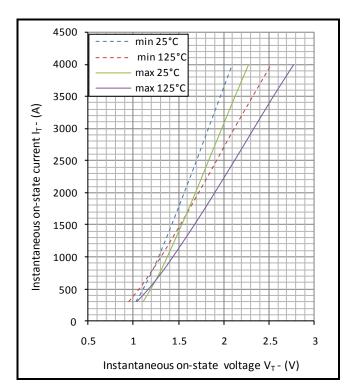


Fig.2 Maximum & minimum on-state characteristics

**V<sub>TM</sub> EQUATION** 

Where

A = 0.259886

 $V_{TM} = A + Bln (I_T) + C.I_T + D.\sqrt{I_T}$ 

B = 0.122742

C = 0.000418

D = -0.002452

these values are valid for  $T_j = 125$ °C for  $I_T 300$ A to 4000A

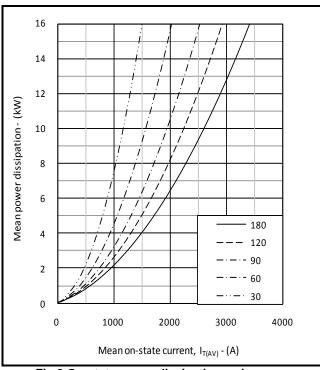


Fig.3 On-state power dissipation - sine wave

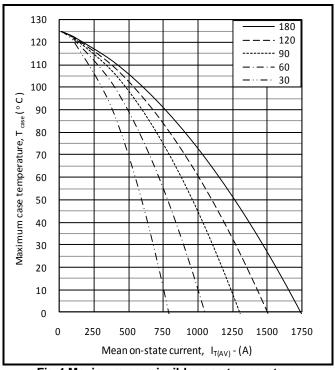


Fig.4 Maximum permissible case temperature, double side cooled – sine wave

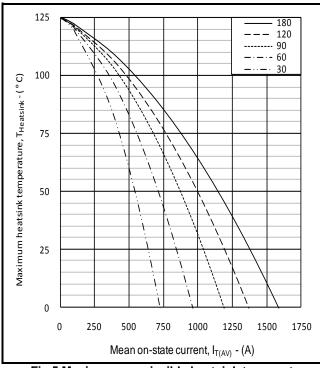


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

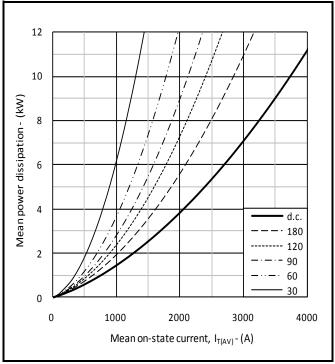


Fig.6 On-state power dissipation - rectangular wave

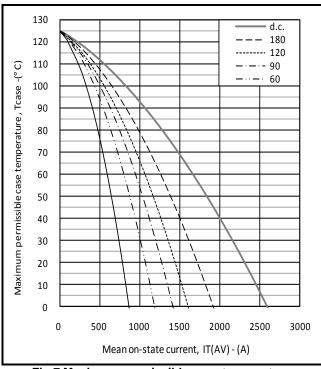


Fig.7 Maximum permissible case temperature, double side cooled - rectangular wave

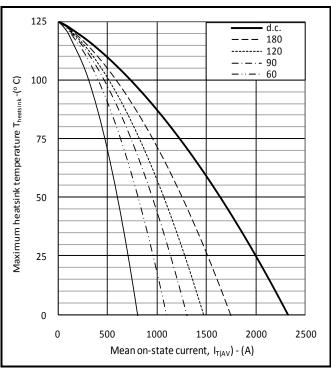
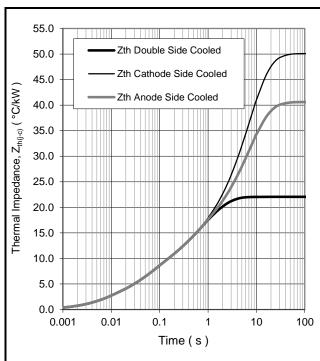


Fig.8 Maximum permissible heatsink temperature, double side cooled - rectangular wave



		1	2	3	4
Double side cooled	R <sub>i</sub> (°C/kW)	3.4733	4.9047	9.1463	4.5220
	T <sub>i</sub> (s)	0.1457	0.0166	1.2832	0.3767
Anode side cooled	R <sub>i</sub> (°C/kW)	7.6674	5.0530	9.7355	27.5992
	T <sub>i</sub> (s)	0.2241	0.0169	4.0566	8.2780
Cathode side cooled	R <sub>i</sub> (°C/kW)	6.0393	4.2782	5.1301	25.0874
	T <sub>i</sub> (s)	0.1356	0.0143	0.6594	7.2358

$$Z_{th} = \sum_{i=1}^{i=4} [R_i \times (1 - \exp(-T/T_i)]$$

## $\Delta R_{th(j-c)}$ Conduction

Tables show the increments of thermal resistance  $R_{\text{th(j-c)}}$  when the device operates at conduction angles other than d.c.

Double side cooling		Anode Side Cooling				Cathode Sided Co		d Cooling		
	$\Delta Z_{th}$ (z)		(z)		ΔZ	th (Z)			$\Delta Z_t$	<sub>h</sub> (z)
$\theta$ °	sine.	rect.		θ°	sine.	rect.		θ°	sine.	rect.
180	3.03	2.07		180	3.03	2.07	İ	180	3.12	2.12
120	3.49	2.95		120	3.49	2.95		120	3.61	3.04
90	3.99	3.43		90	3.99	3.43		90	4.13	3.54
60	4.43	3.94		60	4.43	3.94		60	4.60	4.08
30	4.77	4.49		30	4.76	4.48		30	4.96	4.66
15	4.92	4.77		15	4.92	4.77	I	15	5.13	4.97

Anode Side Cooling					
	$\Delta Z_{th}$ (z)				
θ°	sine.	rect.			
180	3.03	2.07			
120	3.49	2.95			
90	3.99	3.43			
60	4.43	3.94			
30	4.76	4.48			

Cathode Sided Cooling						
	$\Delta Z_{th}$ (z)					
$\theta_{o}$	sine.	rect.				
180	3.12	2.12				
120	3.61	3.04				
90	4.13	3.54				
60	4.60	4.08				
30	4.96	4.66				

Fig.9 Maximum (limit) transient thermal impedance - junction to case (°C/kW)

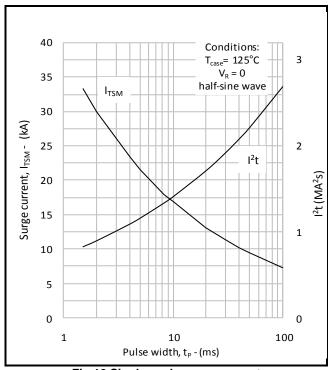


Fig.10 Single-cycle surge current

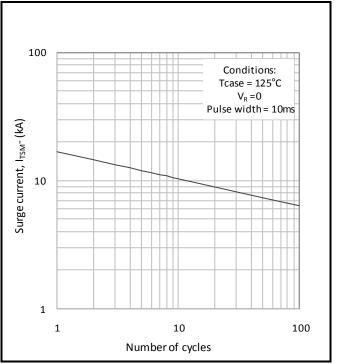


Fig.11 Multi-cycle surge current

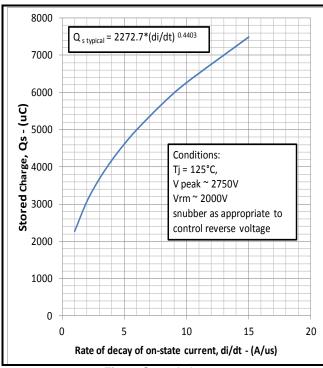


Fig.12 Stored charge

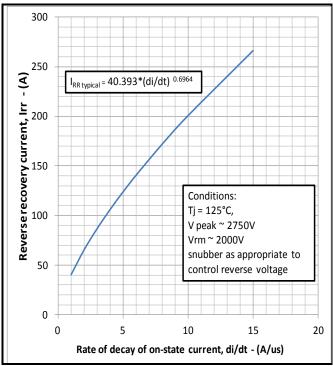


Fig.13 Reverse recovery current

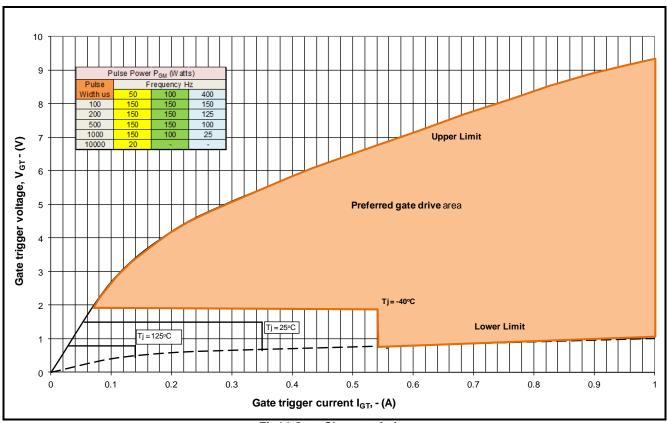


Fig14 Gate Characteristics

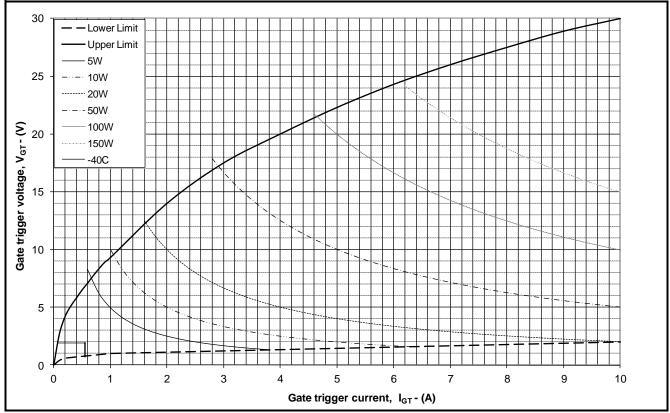


Fig. 15 Gate characteristics



## **PACKAGE DETAILS**

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

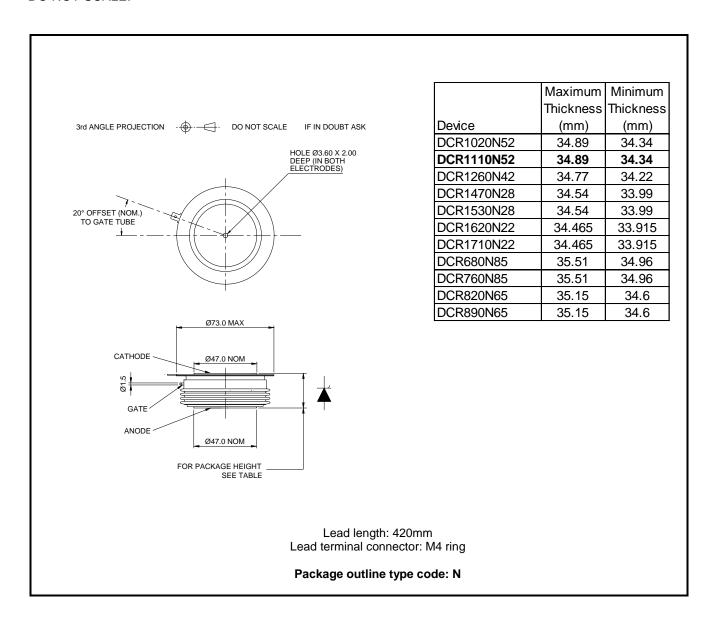


Fig.17 Package outline





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